imall

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1A, 200V - 600V Miniature Ultrafast Glass Passivated Bridge Rectifiers

FEATURES

- Ideal for automated placement, for compact PCB design
- High surge current capability
- Ultrafast reverse recovery time for high frequency
- Negligible leakage current
- Compliant to RoHS Directive 2011/65/EU and in accordance to WEEE 2002/96/EC
- Halogen-free according to IEC 61249-2-21

TYPICAL APPLICATIONS

General purpose rectification for AC/DC bridge full wave rectification for SMPS. PFC function for LED lighting ballast. Also suitable for secondary stage of high frequency inverters.

MECHANICAL DATA

Case: Molded plastic body Molding compound, UL flammability classification rating 94V-0 Moisture sensitivity level: level 1, per J-STD-020 Part no. with suffix "H" means AEC-Q101 qualified Packing code with suffix "G" means green compound (halogen-free) Terminal: Matte tin plated leads, solderable per JESD22-B102 Meet JESD 201 class 2 whisker test Polarity: Polarity as marked on the body Weight: 0.09 g (approximately)

MAXIMUM RATINGS AND ELECTRICAL CHARACTERISTICS (T _A =25°C unless otherwise noted)					
PARAMETER	SYMBOL	EABS1D	EABS1G	EABS1J	UNIT
Maximum repetitive peak reverse voltage	V _{RRM}	200	400	600	V
Maximum RMS voltage	V _{RMS}	140	280	420	V
Maximum DC blocking voltage	V _{DC}	200	400	600	V
Maximum average forward rectified current	I _{F(AV)}	1		А	
Peak forward surge current, 8.3 ms single half sine-wave superimposed on rated load	I _{FSM}	40		А	
Rating for fusing (t<8.3ms)	l ² t	6.64		A ² s	
Maximum instantaneous forward voltage (Note 1) I_F = 1 A	V _F	0.95	1.20	1.70	V
Maximum reverse current @ rated V_R T _J =25°C T _J =125°C	I _R	1 200		μA	
Maximum reverse recovery time (Note 2)	t _{rr}	35		ns	
Typical thermal resistance	R _{θJL} R _{θJA}	25 80		°C/W	
Operating junction temperature range	TJ	- 55 to +150		°C	
Storage temperature range	T _{STG}	- 55 to +150		°C	

Note 1: Pulse test with PW=300 μ s, 1% duty cycle

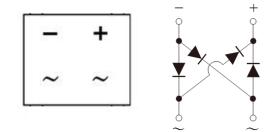
Note 2: Reverse Recovery Test Conditions: I_F =0.5A, I_R =1.0A, I_{rr} =0.25A













Taiwan Semiconductor

ORDERING INFORMATION					
PART NO.	PART NO.	PACKING CODE	PACKING CODE	PACKAGE	PACKING
	SUFFIX		SUFFIX		
EABS1x	Ц	RE	G	ABS	1,000 / 7" Plastic reel
(Note 1)	11	RG	9	ABS	5,000 / 13" Paper reel

Note 1: "x" defines voltage from 200V (EABS1D) to 600V (EABS1J)

Note 2: Whole series with green compound

EXAMPLE					
PREFERRED P/N		PART NO.	PACKING CODE	PACKING CODE	DESCRIPTION
	PART NO.	SUFFIX	PACKING CODE	SUFFIX	DESCHIPTION
EABS1DHREG	EABS1D	Н	RE	G	AEC-Q101 qualified Green compound

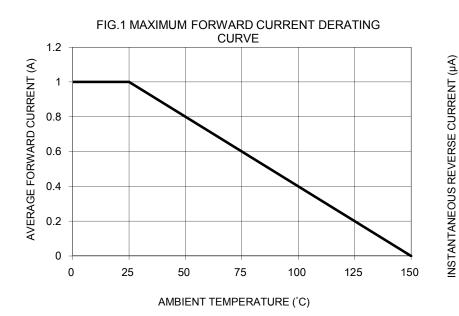
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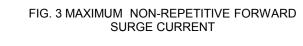
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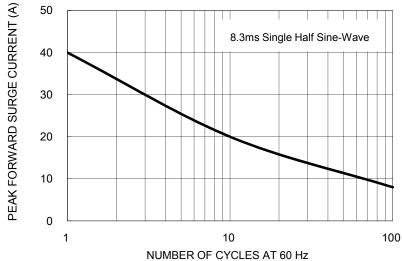
1

RATINGS AND CHARACTERISTICS CURVES

(T_A=25°C unless otherwise noted)







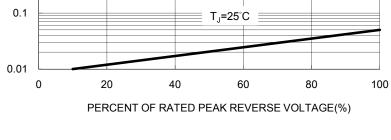
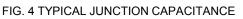
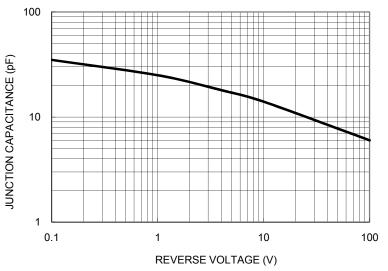


FIG. 2 TYPICAL REVERSE CHARACTERISTICS

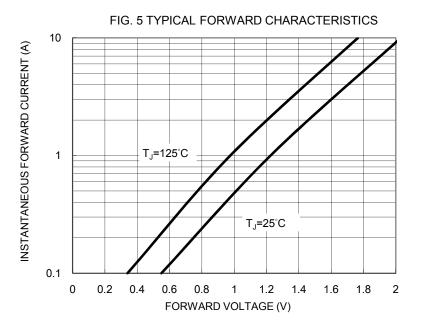
T_J=125°C



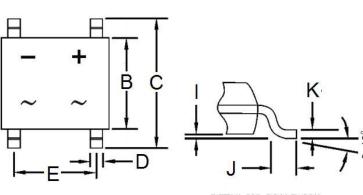


Document Number: DS_D1403002



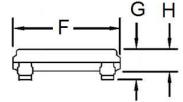


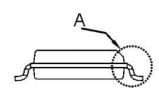
PACKAGE OUTLINE DIMENSIONS ABS



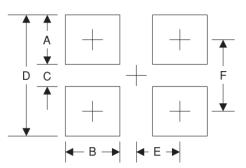
DIM.	Unit	(mm)	Unit (inch)		
DIN.	Min	Max	Min	Max	
В	4.30	4.50	0.169	0.177	
С	6.25	6.65	0.246	0.262	
D	0.60	0.70	0.024	0.028	
E	3.90	4.10	0.154	0.161	
F	4.90	5.10	0.193	0.200	
G	1.40	1.60	0.055	0.063	
Н	1.35	1.45	0.053	0.057	
Ι	0.05	0.15	0.002	0.006	
J	0.30	0.70	0.012	0.028	
K	0.15	0.25	0.006	0.010	

DETAIL "A", SCALE=20/1





SUGGESTED PAD LAYOUT



P/N

YW

F

Symbol	Unit (mm)	Unit (inch)
А	1.5	0.059
В	0.9	0.035
С	4.22	0.166
D	7.22	0.284
E	2.05	0.081
F	5.72	0.225

MARKING DIAGRAM



- = Specific Device Code
- = Date Code
- = Factory Code



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